



Advances on New Silicon-Integrating Devices: From the Technology of Silicon to the Technology with Silicon

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submissions:

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Message from the Guest Editor

Dear Colleagues,

We invite you to contribute to a Special Issue of the journal *Applied Sciences*, “Advances on New Silicon-Integrating Devices: From the Technology of Silicon to the Technology with Silicon”, which aims to present recent advances in next frontiers of silicon technologies and applications that integrate Moore’s Law and the More than Moore concept to write a new paradigm based on the human-driven technology concept. Design and fabrication strategies, modeling and characterization techniques, theoretical studies, and new devices and application fields are welcome.

These important issues include but are not limited to: Silicon, Silicon-on-insulator, Porous silicon, Silicon nanowire, Silicon-on-nothing, Silicon carbide, Low power electronics, Low voltage devices, Three-dimensional integrated circuits, System-in-package, System-on-chip Heterogeneous integration, Sensors, Actuators, Passive components, Biochips, Photonic, Energy harvesting, Photovoltaics, Wireless sensor network, Internet of Things, Automotive, Smart cities, Medicine...





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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